

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM396876

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
KILOPASS TECHNOLOGY, INC.		08/30/2016	Corporation: CALIFORNIA
RECEIVING PARTY DATA			
Name:	Structural Capital Investments II, LP		
Street Address:	3555 Alameda de Las Pulgas		
Internal Address:	Suite 208		
City:	Menlo Park		
State/Country:	CALIFORNIA		
Postal Code:	94025		
Entity Type:	Limited Partnership: DELAWARE		
PROPERTY NUMBERS Total: 3			
Property Type	Number	Word Mark	
Serial Number:	86963998	KILOPASS	
Serial Number:	86964005	K	
Serial Number:	86886054	X2BIT	
CORRESPONDENCE DATA			
Fax Number:	3104845140		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	(310) 440-4100		
Email:	bpoullard@raineslaw.com		
Correspondent Name:	Bunnie Poullard		
Address Line 1:	9720 Wilshire Blvd		
Address Line 2:	5th Floor		
Address Line 4:	Beverly Hills, CALIFORNIA 90212		
NAME OF SUBMITTER:	Bunnie Poullard		
SIGNATURE:	/Bunnie Poullard/		
DATE SIGNED:	08/30/2016		
Total Attachments: 23			
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INTELLECTUAL PROPERTY SECURITY AGREEMENT

This **Intellectual Property Security Agreement** is made as of August 30, 2016 ("*Security Agreement*"), by and between **Kilopass Technology, Inc.**, a California corporation ("*Debtor*"), and **Structural Capital Investment II, L.P.** ("*Lender*").

RECITALS

A. Lender and Debtor are entering into the Loan and Security Agreement, dated as of August 30, 2016 (as the same may be modified, amended, supplemented, restated or superseded from time to time, the "*Loan Agreement*") ,whereby Lender may provide Advances and other financial accommodations to Debtor pursuant to the terms of the Loan Documents. Terms not defined herein shall the meanings ascribed to them in the Loan Agreement.

B. In order to induce Lender to make the Advances, Debtor has agreed to grant a security interest in the Collateral (as defined below) to Lender for purposes of securing the obligations of Debtor to Lender, subject to the terms of this Security Agreement.

NOW, THEREFORE, the parties hereto agree as follows:

1. GRANT OF SECURITY INTEREST. As collateral security for the prompt and complete payment and performance of the Obligations, Debtor hereby grants a security interest to Lender in and to Debtor's entire right, title and interest in, to and under the following intellectual property rights solely to the extent such intellectual property rights pertain to Debtor's one time programmable non-volatile memory technologies (the "*OTP Technologies*"), now or hereafter existing, created, acquired or held by Debtor (all of which shall collectively be called the "*Collateral*");

(a) Any and all copyright rights, copyright applications, copyright registrations and like protections in each work of authorship and derivative work thereof, whether published or unpublished and whether or not the same also constitutes a trade secret, including, without limitation, those set forth on **Exhibit A** attached hereto and incorporated herein by this reference (collectively, the "*Copyrights*").

(b) Any and all trade secrets;

(c) Any and all design rights;

(d) All patents, patent applications and like protections in the United States and outside of the United States including, without limitation, improvements, divisions, continuations, renewals, reissues, extensions and continuations-in-part of the same, including, without limitation, those set forth on **Exhibit B** attached hereto and incorporated herein by this reference (collectively, the "*Patents*");

(e) Any trademark and servicemark rights, whether registered or not, applications to register and registrations of the same and like protections, and the entire goodwill of the business of Debtor connected with and symbolized by such trademarks, including, without limitation, those set forth on **Exhibit C** attached hereto and incorporated herein by this reference (collectively, the "*Trademarks*"); *provided* that the foregoing shall specifically exclude any "intent to use" trademark applications for which a statement of use has not been filed (but only until such statement is filed);

(f) Any and all claims for damages by way of past, present and future infringement of any of the rights included above, with the right, but not the obligation, to sue for and collect such damages for said use or infringement of the intellectual property rights identified above;

(g) All licenses or other rights to use any of the Copyrights, Patents or Trademarks, and all license fees and royalties arising from such use, to the extent permitted by such license or rights;

(h) All amendments, renewals and extensions of any of the Copyrights, Patents or Trademarks; and

(i) All proceeds and products of the foregoing, including, without limitation, all payments under insurance or any indemnity or warranty payable in respect of any of the foregoing.

2. AUTHORIZATION AND REQUEST. Debtor authorizes and requests that the Register of Copyrights and the Commissioner of Patents and Trademarks record this security interest.

3. COVENANTS AND WARRANTIES. Debtor represents, warrants, covenants and agrees as follows:

(a) Debtor is now the sole owner of the Collateral, except for licenses granted by Debtor in the ordinary and normal course of business;

(b) Performance of this Security Agreement does not conflict with or result in a breach of any agreement to which Debtor is a party or by which Debtor is bound, except to the extent that certain intellectual property agreements prohibit the assignment of the rights thereunder to a third party without the licensor's or other party's consent and this Security Agreement constitutes an assignment;

(c) During the term of this Security Agreement, Debtor will not sell, transfer, assign or otherwise encumber any interest in the Collateral, except for (i) licenses and sublicenses granted by Debtor in the ordinary and normal course of its business or as set otherwise permitted in the Loan Documents and (ii) subject to Debtor's execution of appropriate documents, in form acceptable to Lender, to perfect or continue the perfection of Lender's interest in the Collateral, transfers to Affiliates of Debtor;

(d) To its knowledge, each of the Patents is valid and enforceable, and no part of the Collateral has been judged invalid or unenforceable, in whole or in part, and no claim has been made that any part of the Collateral violates the rights of any third party;

(e) Debtor shall promptly advise Lender of any material changes in the composition of the Collateral, including but not limited to any subsequent ownership right of Debtor in or to any Copyright, Patent or Trademark not specified in this Security Agreement in the monthly reporting required in the Loan Agreement;

(f) Debtor shall (i) protect, defend and maintain the validity and enforceability of the Copyrights, Patents and Trademarks material to Debtor's business, (ii) promptly advise Lender in writing of material infringements detected in material Copyrights, Patents and Trademarks, and (iii) not allow any Copyrights, Patents or Trademarks material to Debtor's business to be abandoned, forfeited or dedicated to the public without the written consent of Lender, which shall not be unreasonably withheld, unless Debtor determines that reasonable business practices suggest that abandonment, forfeiture or dedication is appropriate;

(g) Debtor shall, from time to time, execute and file such other instruments, and take such further actions as Lender may reasonably request from time to time to perfect or continue the perfection of Lender's interest in the Collateral;

(h) This Security Agreement creates, and in the case of after acquired Collateral, this Security Agreement will create at the time Debtor first has rights in such after acquired Collateral, in favor of Lender a valid and perfected first priority security interest in the Collateral in the United States securing the payment and performance of all Obligations upon making the filings referred to in **Section 3(i)** below, subject only to Permitted Liens;

(i) To its knowledge, except for, and upon, the filings with, as applicable, (1) the United States Patent and Trademark office with respect to the Patents and Trademarks, (2) the Register of Copyrights with respect to the Copyrights and (3) the California Secretary of State, necessary to perfect the security interests created hereunder, and except as has been already made or obtained, no authorization, approval or other action by, and no notice to or filing with, any United States governmental authority or United States regulatory body is required either (a) for the grant by Debtor of the security interest granted hereby or for the execution, delivery or performance of this Security Agreement by Debtor in the United States or (b) for the perfection in the United States of the security interest granted to Lender herein;

(j) All information heretofore, herein or hereafter supplied to Lender by or on behalf of Debtor with respect to the Collateral is accurate and complete in all material respects;

(k) Debtor shall not enter into any agreement that would materially impair or conflict with Debtor's obligations hereunder without Lender's prior written consent, which consent shall not be unreasonably withheld or delayed. Debtor shall not permit the inclusion in any material contract¹ to which it becomes a party of any provisions that could or might in any way prevent the creation of a security interest in Debtor's rights and interests in any property included within the definition of the Collateral acquired under such contracts; and

(l) Upon any executive officer of Debtor obtaining actual knowledge thereof, Debtor will promptly notify Lender in writing of any event that materially adversely affects the value of any material Collateral, the ability of Debtor to dispose of any material Collateral or the rights and remedies of Lender in relation thereto, including the levy of any legal process against any of the material Collateral.

4. LENDER'S RIGHTS. Lender shall have the right, but not the obligation, to take, at Debtor's sole expense, any actions that Debtor is required under this Security Agreement to take but which Debtor fails to take, after fifteen (15) days' written notice to Debtor. In accordance with the provisions of the Loan Agreement, Debtor shall reimburse and indemnify Lender for all reasonable costs and reasonable Lender Expenses incurred in the reasonable exercise of its rights under this **Section 4**.

5. FURTHER ASSURANCES; ATTORNEY IN FACT.

(a) On a quarterly basis, Debtor agrees to deliver to Lender a report, in form acceptable to Lender and certified by an officer of Debtor, which lists all Copyrights, Patents and Trademarks that are material to the operation of Debtor's business on an on-going basis, and in which Lender does not already have a perfected security interest (the "*Quarterly Report*"); *provided, however*, Debtor may provide a general description of the Copyrights by type.

(b) On a continuing basis upon Lender's written request, Debtor will take all such action as may reasonably be necessary or advisable, or as reasonably requested by Lender, to perfect Lender's security interest in all Collateral including any hereafter acquired Collateral, and otherwise to carry out the intent and purposes of this Security Agreement, or for assuring and confirming to Lender the grant or perfection of a security interest in all Collateral.

6. EVENTS OF DEFAULT. The occurrence of any of the following shall constitute an "Event of Default" under this Security Agreement:

(a) An Event of Default occurs under the Loan Agreement or any of the other Loan Documents; or

(b) Debtor breaches any warranty or covenant or agreement in any material respect made by Debtor in this Security Agreement and, as to any breach that is capable of cure, Debtor fails to cure such breach within fifteen (15) days of the occurrence of such breach following written notice thereof to Debtor.

7. REMEDIES. Upon the occurrence and during the continuance of an Event of Default, Lender shall have the right to exercise all the remedies under the Loan Agreement, and that of a secured party under the California Uniform Commercial Code, including, without limitation, the right to require Debtor to assemble the Collateral and any tangible property in which Lender has a security interest and to make it available to Lender at a place designated by Lender. Lender shall have a nonexclusive, royalty free license to use the Copyrights, Patents and Trademarks to the extent reasonably necessary to permit Lender to exercise its rights and remedies upon the occurrence and during the continuance of an Event of Default. In accordance with the provisions of the Loan Agreement, Debtor will pay any Lender Expenses in connection with the exercise of any of Lender's rights hereunder. All of Lender's rights and remedies with respect to the Collateral shall be cumulative.

8. RELEASE OF SECURITY INTEREST; STANDSTILL ON REMEDIES.

(a) Upon the payment and satisfaction in full of all Obligations (other than inchoate indemnity obligations), the security interests hereunder shall automatically terminate and Lender shall execute and deliver to Debtor all deeds, assignments, releases, terminations, filings and other instruments as may be necessary or proper to release Lender's security interests hereunder.

(b) Notwithstanding any provision hereof or in any other Loan Document to the contrary, upon the occurrence of an Event of Default hereunder or under the Loan Agreement, Lender shall forebear from exercising its rights under Section 7 hereunder with respect to Lender's foreclosure on, ownership or possession of, or sale of the Collateral (as defined in this Security Agreement only) until the latter of (i) a period of [ninety (90)] days following the date of the Event of Default, or (ii) the date upon which any party other than Lender asserts, perfects, files, creates and/or acts upon a Lien, judgement, attachment, seizure or foreclosure action on any portion of the Collateral (as defined in this Security Agreement) regardless of whether such action (or failure to act) would constitute an Event of Default hereunder or under the Loan Agreement, or (iii) the date upon which Borrower (or its Board of Directors) authorizes or permits the creation of a Lien, judgement, attachment, seizure or foreclosure action on any portion of the Collateral (as defined in this Security Agreement) regardless of whether such action (or failure to act) would constitute an Event of Default hereunder or under the Loan Agreement (the "Forbearance Period"). Upon the termination of the Forbearance Period, and without the need for any notification, demand, or consent by Lender or Debtor, Lender shall be entitled to exercise any or all of its rights and remedies hereunder, or under the Loan Agreement, or under applicable law with respect to the Collateral (as defined in this Security Agreement). Nothing herein shall be deemed a waiver by Lender of any of its rights or remedies arising under any other Loan Document, or under applicable law, nor shall this Section 9(b) be deemed a waiver of any Default or Event of Default under any Loan Document including this Security Agreement. Nothing in this Section 9(b) shall require Lender to exercise any rights or remedies following the Forbearance Period or otherwise, and the failure to exercise such rights and remedies shall not be deemed a waiver thereof.

10. NO FAILURE OR DELAY. No failure or delay on the part of Lender, in the exercise of any power, right or privilege hereunder shall operate as a waiver thereof, nor shall any single or partial exercise thereof.

11. ATTORNEYS' FEES. If any action relating to this Security Agreement is brought by either party hereto against the other party, the prevailing party shall be entitled to recover reasonable attorneys' fees, costs and disbursements.

12. AMENDMENTS. This Security Agreement may be amended only by a written instrument signed by Lender and Debtor, except amendments made pursuant to Section 5 hereto.

13. COUNTERPARTS. This Security Agreement may be executed in any number of counterparts, each of which when so delivered shall be deemed an original, but all such counterparts shall constitute but one and the same instrument. Each such Security Agreement shall become effective upon the execution of a counterpart hereof or thereof by each of the parties hereto and telephonic notification that such executed counterparts has been received by Debtor and Lender.

14. CHOICE OF LAW AND VENUE; JURY TRIAL WAIVER.

This Agreement shall be governed by, and construed in accordance with, the internal laws of the State of California, without regard to principles of conflicts of law. Each of Debtor and Lender hereby submits to the exclusive jurisdiction of the state and Federal courts located in the County of San Mateo, State of California. DEBTOR AND LENDER EACH HEREBY WAIVE THEIR RESPECTIVE RIGHTS TO A JURY TRIAL OF ANY CLAIM OR CAUSE OF ACTION BASED UPON OR ARISING OUT OF THIS AGREEMENT OR ANY OF THE TRANSACTIONS CONTEMPLATED HEREIN, INCLUDING CONTRACT CLAIMS, TORT CLAIMS, BREACH OF DUTY CLAIMS, AND ALL OTHER COMMON LAW OR STATUTORY CLAIMS. EACH PARTY RECOGNIZES AND AGREES THAT THE FOREGOING WAIVER CONSTITUTES A MATERIAL INDUCEMENT FOR IT TO ENTER INTO THIS AGREEMENT. EACH PARTY REPRESENTS AND WARRANTS THAT IT HAS REVIEWED THIS WAIVER WITH ITS LEGAL COUNSEL AND THAT IT KNOWINGLY AND VOLUNTARILY WAIVES ITS JURY TRIAL RIGHTS FOLLOWING CONSULTATION WITH LEGAL COUNSEL.

IF THE FOREGOING JURY TRIAL WAIVER IS FOR ANY REASON UNENFORCEABLE, THE PARTIES AGREE TO RESOLVE ALL CLAIMS, CAUSES AND DISPUTES THROUGH JUDICIAL REFERENCE PURSUANT TO CODE OF CIVIL PROCEDURE SECTION 638 ET SEQ., BEFORE A MUTUALLY ACCEPTABLE REFEREE IN SAN MATEO COUNTY SITTING WITHOUT A JURY OR, IF THE PARTIES CANNOT AGREE ON A REFEREE, THEN ONE APPOINTED BY THE PRESIDING JUDGE OF THE CALIFORNIA SUPERIOR COURT FOR SAN MATEO COUNTY, CALIFORNIA. NOTHING IN THIS SECTION SHALL RESTRICT A PARTY FROM EXERCISING PRE-JUDGMENT REMEDIES OR ITS RIGHTS UNDER THE UNIFORM COMMERCIAL CODE.

THIS SECTION INTENTIONALLY LEFT BLANK

IN WITNESS WHEREOF, the parties hereto have executed this Security Agreement on the day and year first above written.

DEBTOR :

KILOPASS TECHNOLOGY, INC.,

a California corporation

DocuSigned by:
Charlie Cheng

By: 5351F8B05C614D7...

Name: Charlie Cheng

Title: CEO

LENDER:

STRUCTURAL CAPITAL INVESTMENTS II, LP, a

Delaware limited partnership

By: STRUCTURAL CAPITAL GP II, LLC,

a Delaware limited liability company

its General Partner

DocuSigned by:
Larry Gross

By: BB706469BF9A44C...

Name: Larry Gross

Title: Managing Member

Exhibit A
COPYRIGHTS

1. REGISTERED:

None

2. UNREGISTERED:

Product designs, marketing material, and all other copyrightable material owned by Kilopass

3. APPLICATIONS IN PROCESS: None

Exhibit
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Exhibit B**U.S. AND NON U.S. PATENTS AND PATENT APPLICATIONS**

Patent Title	Patent Status	Filing Date	Issue Date	App. Number	Country	Patent Number
3.5 Transistor Non-volatile Memory Cell Using Gate Breakdown Phenomena	Issued	3/13/2006	11/21/2008	95108467	Taiwan	I303424
3.5 Transistor Non-volatile Memory Cell Using Gate Breakdown Phenomena	Issued	10/18/2006	8/12/2009		China	ZL 200610142513.1
3.5 Transistor Non-volatile Memory Cell Using Gate Breakdown Phenomena	Issued	4/4/2006	7/20/2013	2006-102753	Japan	5043357
3.5 Transistor Non-volatile Memory Cell Using Gate Breakdown Phenomena	Issued	10/18/2005	2/6/2007	11/252,461	United States of America	7,173,851
3.5 Transistor Non-volatile Memory Cell	Issued	3/28/2006	5/28/2008	EP2006251693	European Patent Office	1,777,708

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Using Gate Breakdown Phenomena					(EPO)	
3.5-transistor Non-volatile Memory Cell Using Gate Breakdown Phenomena	Issued	3/28/2006	5/28/2008		France	1,777,708
3.5-transistor Non-volatile Memory Cell Using Gate Breakdown Phenomena	Issued	3/28/2006	5/28/2008		United Kingdom	1,777,708
3.5-transistor Non-volatile Memory Cell Using Gate Breakdown Phenomena	Issued	3/28/2006	5/28/2008		Germany	1,777,708
Electrically Programmable Fuse Bit	Issued	1/29/2007	11/15/2013	10-2013-7002716	Republic of Korea (South)	1332121
Electrically Programmable Fuse Bit	Issued	1/29/2007	4/5/2013	2008-552612	Japan	5237116
Electrically Programmable Fuse Bit	Issued	1/29/2007	2/11/2014	10-2008-7020920	Republic of Korea (South)	10-1364370
Electrically Programmable	Issued	1/29/2007	4/11/2014	10-2013-	Republic of Korea	1386781

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Fuse Bit				7015883	(South)	
Electrically Programmable Fuse Bit	Issued	1/29/2007	11/21/2012	7710366.1	United Kingdom	1979912
Electrically Programmable Fuse Bit	Issued	1/29/2007	2/1/2012	2.0078E+11	China	
Electrically Programmable Fuse Bit	Issued	1/29/2007	11/21/2012	7710366.1	France	1979912
Electrically Programmable Fuse Bit	Issued	1/29/2007	11/21/2012	7710366.1	Germany	6.02007E+11
Electrically Programmable Fuse Bit	Issued	1/29/2007	10/27/2009	11/699,916	United States of America	7,609,539
Electrically Programmable Fuse Bit	Issued	10/9/2009	3/15/2011	12/577,084	United States of America	7,907,465
High Density Semiconductor Memory Cell And Memory Array Using A Single Transistor And Having Counter-Doped Poly And Buried Diffusion Wordline	Issued	3/10/2004	1/31/2006	10/798,753	United States of America	6,992,925

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High Density Semiconductor Memory Cell And Memory Array Using A Single Transistor And Having Counter-Doped Poly And Buried Diffusion Wordline	Issued	3/10/2005	6/10/2009	2.0051E+11	China	ZL200510052717 .1
High Density Semiconductor Memory Cell And Memory Array Using A Single Transistor And Having Variable Gate Oxide Breakdown	Issued	1/26/2004	9/6/2005	10/765,802	United States of America	6,940,751
High Density Semiconductor Memory Cell And Memory Array Using A Single Transistor Having A Buried N+ Connection	Issued	10/2/2003	5/24/2005	10/677,613	United States of America	6,898,116
High Density Semiconductor Memory Unit And Memory	Issued	4/26/2002	8/17/2004	10/133,704	United States of America	6,777,757

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Array Using Single Transistor						
High Density Semiconductor Memory Unit And Memory Array Using Single Transistor	Issued		11/30/2005		China	ZL 03117374.8
High Density Semiconductor Memory Unit And Memory Array Using Single Transistor	Issued	4/22/2003	3/13/2013	3751752.1	Germany	60343511.4
High Density Semiconductor Memory Unit And Memory Array Using Single Transistor	Issued	4/25/2003	9/12/2006	92109813	Taiwan	261918
High Density Semiconductor Memory Unit And Memory Array Using Single Transistor	Issued	4/22/2003	3/13/2013	3751752.1	United Kingdom	1579479
High Density Semiconductor	Issued	4/22/2003	3/13/2013	3751752.1	France	1579479

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Memory Unit And Memory Array Using Single Transistor						
High Density Semiconductor Memory Unit And Memory Array Using Single Transistor	Issued	10/21/2004	11/20/2009		Japan	4410101
High Density Semiconductor Memory Unit And Memory Array Using Single Transistor	Issued	5/30/2003	2/15/2005	10/448,505	United States of America	6,856,540
Memory Transistor Gate Oxide Stress Release And Improved Reliability	Issued	3/6/2006	9/11/2007	11/368,576	United States of America	7,269,047
Method And Apparatus For Programming Auto Shut-off	Issued	8/29/2008	2/14/2012	12/202,048	United States of America	8,116,145
Method Of Testing The Thin Oxide Of A Semiconductor	Issued	10/30/2003	7/22/2009		China	ZL 200310110823.1

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Memory Cell That Uses Breakdown Voltage						
Method Of Testing The Thin Oxide Of A Semiconductor Memory Cell That Uses Breakdown Voltage	Issued	3/23/2004	6/11/2005	93107848	Taiwan	234162
Method Of Testing The Thin Oxide Of A Semiconductor Memory Cell That Uses Breakdown Voltage	Issued	4/2/2003	9/14/2004	10/406,406	United States of America	6,791,891
Method Of Testing The Thin Oxide Of A Semiconductor Memory Cell That Uses Breakdown Voltage	Issued		7/22/2009		China	ZL 200310110823.1
Methods And Circuits For Programming Of A Semiconductor Memory Cell	Issued	6/2/2004	5/9/2006	10/859,934	United States of America	7,042,772

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And Memory Array Using A Breakdown Phenomenon In An Ultra-Thin Dielectric						
Methods And Circuits For Programming Of A Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomenon In An Ultra-Thin Dielectric	Issued	3/9/2005	1/27/2010	ZL 2005100543 87.X	China	100585738
Methods And Circuits For Testing Programmability Of A Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomenon In An Ultra-Thin Dielectric	Issued	3/9/2004	4/18/2006	10/796,270	United States of America	7,031,209
Non-volatile Semiconductor Memory Based On Enhanced	Issued	12/8/2008	11/24/2009	12/330,465	United States of America	7,623,368

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Gate Oxide Breakdown						
Non-volatile Semiconductor Memory Based On Enhanced Gate Oxide Breakdown	Issued	1/24/2007	12/30/2008	11/657,982	United States of America	7,471,540
One-time Programmable Memory	Issued	6/2/2010	10/9/2012	12/802,206	United States of America	8,283,731
One-time Programmable Memory And Method For Making The Same	Issued	4/10/2014	1/5/2016	14/250,267	United States of America	9,230,813
One-time Programmable Memory And Method For Making The Same	Issued	6/21/2010	12/11/2012	12/819,566	United States of America	8,330,189
Programming Methods And Circuits For Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin	Issued		1/31/2007		China	ZL 03117372.1

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Dielectric						
Programming Methods And Circuits For Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	9/26/2002	12/30/2003	10/256,483	United States of America	6,671,040
Reduced Bit Line Leakage Current In Non-volatile Memories	Issued	9/20/2007	9/8/2009		United States of America	7,586,787
Reprogrammable Non-volatile Memory Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued		1/26/2005		China	ZL 01129152.4
Reprogrammable Non-volatile Memory Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	10/15/2002	7/30/2010		Japan	4,559,080

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Reprogrammable Non-volatile Memory Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	10/16/2002	9/3/2004	91123860	Taiwan	201454
Reprogrammable Non-volatile Memory Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	10/3/2002	10/18/2005	10/264,212	United States of America	6,956,258
Reprogrammable Non-volatile Memory Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	10/17/2001	3/2/2004	09/982,314	United States of America	6,700,151
Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	9/17/2002	3/3/2010	60235562.1	Germany	1,436,815
Semiconductor Memory Cell And Memory Array Using A Breakdown	Issued	9/17/2002	3/3/2010		France	1,436,815

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Phenomena In An Ultra-Thin Dielectric						
Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	9/17/2002	10/1/2010		Japan	4,599,059
Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	12/17/2001	12/23/2003	10/024,327	United States of America	6,667,902
Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	8/11/2003	11/23/2004	10/639,041	United States of America	6,822,888
Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	9/18/2002	7/9/2004	91121385	Taiwan	198223

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Dielectric						
Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	9/18/2001	9/28/2004	09/955,641	United States of America	6,798,693
Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	9/17/2002	3/3/2010		United Kingdom	1,436,815
Semiconductor Memory Cell And Memory Array Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued		2/23/2005		China	ZL 01129151.6
Semiconductor Memory Cell, Memory Array And Method For Operating The Same	Issued		8/5/2009	3809184.4	China	ZL03809184.4

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Smart Card Having Memory Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	10/16/2002	6/21/2005	91123859	Taiwan	234785
Smart Card Having Memory Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued	10/17/2001	7/27/2004	09/982,034	United States of America	6,766,960
Smart Card Having Memory Using A Breakdown Phenomena In An Ultra-Thin Dielectric	Issued		6/14/2006		China	ZL 01129150.8
One-Time programmable Memory and Method for Making the Same	To Be Issued	4/8/2015	8/30/2016	14/681,852	United States of America	9,431,254
Low-Power Read for OTP Memory Arrays	Pending	5/11/2016		15/152,463	United States of America	
Write Enhancement for One-Time	Pending	5/13/2016		15/154,911	United States of America	

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Programmable (OTP) Semiconductors						
Memory Sensing Architecture Patent	Pending	6/21/2016		15/188,166	United States of America	

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Exhibit C

U.S. AND NON U.S. TRADEMARKS AND TRADEMARK APPLICATIONS

(List marks below or indicate "None")

Registration No.	Pending Application No.	Mark	Registration Date	Filing Date
	86/963,998	KILOPASS		4/5/2016
	86/964,005	K DESIGN		4/5/2016
	86/886,054	X2BIT		1/25/2016

UNREGISTERED TRADEMARKS: List marks below or indicate "None."

Gusto, XPM